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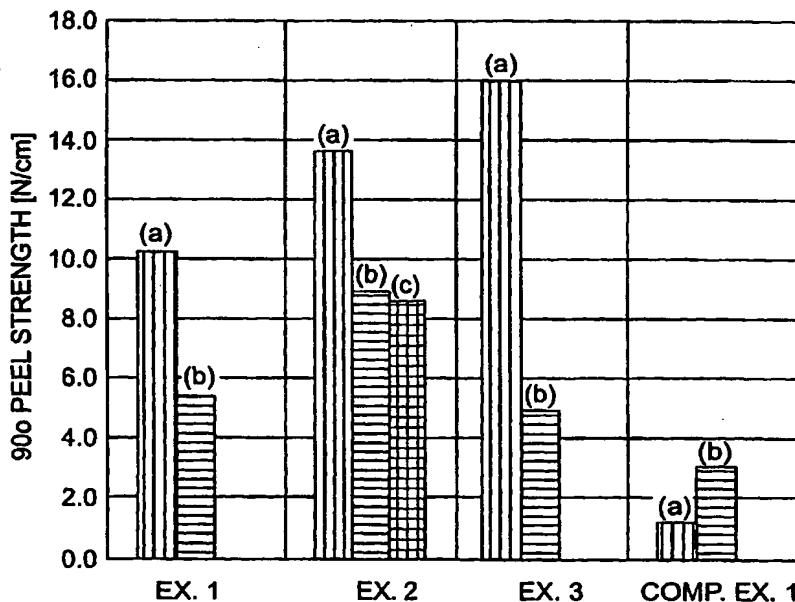
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(54) Title: HEAT-CURABLE ADHESIVE COMPOSITION



(57) Abstract: The present invention provides a heat-curable adhesive composition comprising ethylene-glycidyl (meth)acrylate copolymer, low density polyethylene, ethylene- α -olefin copolymer, and a heat curing agent for the ethylene-glycidyl (meth)acrylate copolymer.